Emeka H Amalu

List of Publications by Year
in descending order

Source: https://exaly.com/author-pdf/861571/publications.pdf

Version: 2024-02-01

18	608	759233 12	1058476 14
papers	citations	h-index	g-index

18	18	18	536
all docs	docs citations	times ranked	citing authors

#	ARTICLE	IF	CITATIONS
1	A review of interconnection technologies for improved crystalline silicon solar cell photovoltaic module assembly. Applied Energy, 2015, 154, 173-182.	10.1	115
2	A review of photovoltaic module technologies for increased performance in tropical climate. Renewable and Sustainable Energy Reviews, 2017, 75, 1225-1238.	16.4	80
3	Effect of operating temperature on degradation of solder joints in crystalline silicon photovoltaic modules for improved reliability in hot climates. Solar Energy, 2018, 170, 682-693.	6.1	63
4	High temperature reliability of lead-free solder joints in a flip chip assembly. Journal of Materials Processing Technology, 2012, 212, 471-483.	6.3	60
5	Evaluation of thermo-mechanical damage and fatigue life of solar cell solder interconnections. Robotics and Computer-Integrated Manufacturing, 2017, 47, 37-43.	9.9	49
6	Thermal fatigue life of ball grid array (BGA) solder joints made from different alloy compositions. Engineering Failure Analysis, 2021, 125, 105447.	4.0	49
7	Modelling evaluation of Garofalo-Arrhenius creep relation for lead-free solder joints in surface mount electronic component assemblies. Journal of Manufacturing Systems, 2016, 39, 9-23.	13.9	47
8	Effective Solder for Improved Thermo-Mechanical Reliability of Solder Joints in a Ball Grid Array (BGA) Soldered on Printed Circuit Board (PCB). Journal of Electronic Materials, 2021, 50, 263-282.	2.2	29
9	Damage of lead-free solder joints in flip chip assemblies subjected to high-temperature thermal cycling. Computational Materials Science, 2012, 65, 470-484.	3.0	22
10	Optimisation of thermo-fatigue reliability of solder joints in surface mount resistor assembly using Taguchi method. Finite Elements in Analysis and Design, 2015, 107, 13-27.	3.2	19
11	A review of technology, materials and R&D challenges of upper limb prosthesis for improved user suitability. Journal of Orthopaedics, 2021, 23, 88-96.	1.3	17
12	Investigation of effects of heat sinks on thermal performance of microelectronic package. , 2011, , .		16
13	Prediction of damage and fatigue life of high-temperature flip chip assembly interconnections at operations. Microelectronics Reliability, 2012, 52, 2731-2743.	1.7	14
14	High-temperature fatigue life of flip chip lead-free solder joints at varying component stand-off height. Microelectronics Reliability, 2012, 52, 2982-2994.	1.7	12
15	Creep Damage of BGA Solder Interconnects Subjected to Thermal Cycling and Isothermal Ageing. , 2019, , .		5
16	Effect of component standoff height on thermo-mechanical reliability of ball grid array (BGA) solder joints operating in high-temperature ambient. , 2015, , .		4
17	Effect of Relative Density on Compressive Load Response of Crumpled Aluminium Foil Mesh. Materials, 2019, 12, 4018.	2.9	4
18	Comparing and Benchmarking Fatigue Behaviours of Various SAC Solders under Thermo-Mechanical Loading. , 2020, , .		3